



Gp 11732

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Electronic Patent Application Submission  
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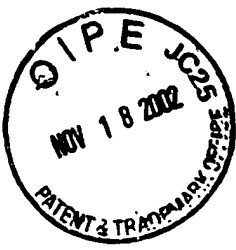
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TC 1700

EFS ID: 19987  
Application ID: 10087050  
Title of Invention: METHOD OF MAKING A  
COMPOSITE PANEL AND ARTICLE  
MADE THEREBY  
First Named Inventor: Phillip Carroll  
Domestic/Foreign Application: Domestic Application  
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Submission Type: Information  
Disclosure Statement

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**TC 1700**

Application Number: 10087050

Attorney Docket Number: OAKW0124PUS

## **METHOD OF MAKING A COMPOSITE PANEL AND ARTICLE MADE THEREBY**

First Named Inventor: Phillip P. Carroll III

### SUBMITTED BY

Name: Matthew R. Mowers  
Registration Number: 44956  
Electronic Signature  
Mark: /s/Matthew R. Mowers  
Date Signed: 20021118

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### Attached Files:

us-information-disclosure-statement 1OAKW0124PUSids.xml

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